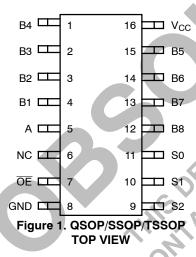
8:1 Multiplexer/ Demultiplexer Bus Switch

The ON Semiconductor 74FST3251 is an 8:1, high performance multiplexer/demultiplexer bus switch. The device is CMOS TTL compatible when operating between 4 and 5.5 Volts. The device exhibits extremely low $R_{\rm ON}$ and adds nearly zero propagation delay. The device adds no noise or ground bounce to the system.

Features

- $R_{ON} < 4 \Omega$ Typical
- Less Than 0.25 ns-Max Delay Through Switch
- Nearly Zero Standby Current
- No Circuit Bounce
- Control Inputs are TTL/CMOS Compatible
- All Popular Packages: QSOP-16, TSSOP-16, SOIC-16
- All Devices in Package TSSOP are Inherently Pb-Free*



TRUTH TABLE

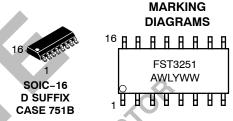
	Inp	uts		
OE	S2	S1	S0	Function
L	L	L ((O)	A Port = B1 Port
L	L	L	Н	A Port = B2 Port
L	L	Ħ	L	A Port = B3 Port
L	L	Н	Н	A Port = B4 Port
L	Н	L	L	A Port = B5 Port
L	Н	L	Н	A Port = B6 Port
L	Н	Н	L	A Port = B7 Port
L	Н	Н	Н	A Port = B8 Port
Н	Х	Х	Х	Disconnect

NOTE: H = HIGH Voltage Level, L = LOW Voltage Level, X = Don't Care



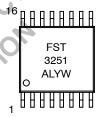
ON Semiconductor®

http://onsemi.com



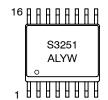


TSSOP-16 DT SUFFIX CASE 948F





QSOP-16 QS SUFFIX CASE 492



A = Assembly Location
L, WL = Wafer Lot
Y = Year

Work Week

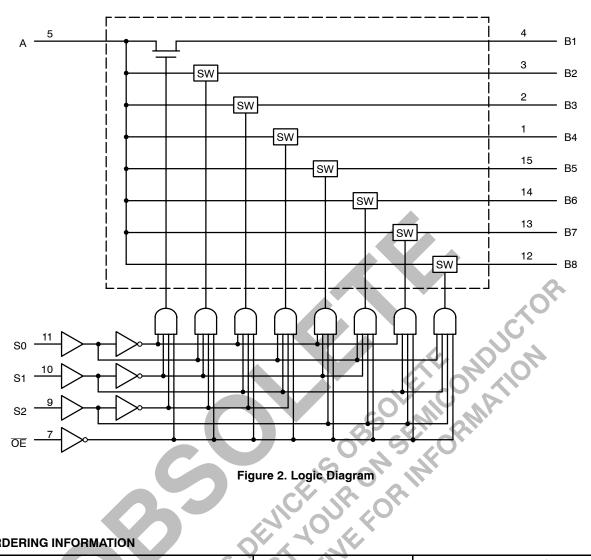
PIN NAMES

Pin	Description
\overline{OE}_1 , \overline{OE}_2	Bus Switch Enables
S ₀ , S ₁	Select Inputs
А	Bus A
B ₁ , B ₂ , B ₃ , B ₄	Bus B

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ORDERING INFORMATION

Device Order Number	Package	Shipping [†]
74FST3251D	SOIC-16	48 Units / Rail
74FST3251DR2	SOIC-16	1000 Units / Tape & Reel
74FST3251DT	TSSOP-16* (Pb-Free)	96 Units / Rail
74FST3251DTR2	TSSOP-16* (Pb-Free)	2500 Units / Tape & Reel
74FST3251QS	QSOP-16	96 Units / Rail
74FST3251QSR	QSOP-16	2500 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}This package is inherently Pb-Free.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	-0.5 to +7.0	V
Vo	DC Output Voltage	-0.5 to +7.0	V
I _{IK}	DC Input Diode Current $V_1 < GND$	-50	mA
I _{OK}	DC Output Diode Current V _O < GND	-50	mA
Io	DC Output Sink Current	128	mA
I _{CC}	DC Supply Current per Supply Pin	± 100	mA
I _{GND}	DC Ground Current per Ground Pin	± 100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	+ 150	°C
$\theta_{\sf JA}$	Thermal Resistance SOIC TSSOP QSOP	125 170 200	°C/W
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 1) Machine Model (Note 2) Charged Device Model (Note 3)	> 2000 > 200 N/A	٧
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 85°C (Note 4)	±500	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. Tested to EIA/JESD22-A114-A.
- 2. Tested to EIA/JESD22-A115-A.
- 3. Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating, Data Retention Only	4.0	5.5	V
VI	Input Voltage (Note)	0	5.5	V
Vo	Output Voltage (HIGH or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature	-40	+85	°C
Δt/ΔV		0	DC 5	ns/V

5. Unused control inputs may not be left open. All control inputs must be tied to a high or low logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

			V _{cc}	T _A = -	40°C to	+85°C	
Symbol	Parameter	Conditions	(V)	Min	Тур*	Max	Unit
V _{IK}	Clamp Diode Resistance	$I_{IN} = -18mA$	4.5			-1.2	V
V _{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V _{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
lı	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	5.5			±1.0	μΑ
l _{OZ}	OFF-STATE Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μΑ
R _{ON}	Switch On Resistance (Note 6)	V _{IN} = 0 V, I _{IN} = 64 mA	4.5		4	7	Ω
		V _{IN} = 0 V, I _{IN} = 30 mA	4.5		4	7	
		V _{IN} = 2.4 V, I _{IN} = 15 mA	4.5		8	15	
		V _{IN} = 2.4 V, I _{IN} = 15 mA	4.0		11	20	
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND, I _{OUT} = 0	5.5			3	μΑ
ΔI_{CC}	Increase In I _{CC} per Input	One input at 3.4 V, Other inputs at V_{CC} or GND	5.5			2.5	mA

AC ELECTRICAL CHARACTERISTICS

			$T_A = -40$ °C to $+85$ °C $C_L = 50$ pF, RU = RD = 500 Ω				
		05	V _{CC} = 4	.5-5.5 V	V _{CC} =	4.0 V	
Symbol	Parameter	Conditions	Min	Max	Min	Max	Unit
t _{PHL} , t _{PLH}	Prop Delay Bus to Bus (Note 7)	V _I = OPEN		0.25		0.25	ns
	Prop Delay, Select to Bus A	4, 0	1.0	6.3		6.9	
t _{PZH} , t _{PZL}	Output Enable Time, Select to Bus B	$V_I = 7 \text{ V for } t_{PZL}$	1.0	6.0		6.5	ns
	Output Enable Time, I _{OE} to Bus A, B	$V_I = OPEN$ for t_{PZH}	1.0	6.0		6.5	
t _{PHZ} , t _{PLZ}	Output Disable Time, Select to Bus B	$V_I = 7 V \text{ for } t_{PLZ}$	1.0	5.8		6.5	ns
	Output Disable Time, I _{OE} to Bus A, B	$V_I = OPEN$ for t_{PHZ}	1.0	5.8		6.5	

^{7.} This parameter is guaranteed by design but is not tested. The bus switch contributes no propagation delay other than the RC delay of the typical On resistance of the switch and the 50 pF load capacitance, when driven by an ideal voltage source (zero output impedance).

CAPACITANCE (Note 8)

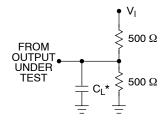
Symbol	Parameter	Conditions	Тур	Max	Unit
C _{IN}	Control Pin Input Capacitance	V _{CC} = 5.0 V	3		pF
C _{I/O}	A Port Input/Output Capacitance	V _{CC} , OE = 5.0 V	13		pF
C _{I/O}	B Port Input/Output Capacitance	V _{CC} , OE = 5.0 V	5		pF

^{8.} $T_A = +25$ °C, f = 1 MHz, Capacitance is characterized but not tested.

^{*}Typical values are at V_{CC} = 5.0 V and T_A = 25°C.

6. Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.

AC Loading and Waveforms



NOTES:

- 1. Input driven by 50 Ω source terminated in 50 $\Omega.$
- 2. CL includes load and stray capacitance.
- $*C_L = 50 pF$

Figure 3. AC Test Circuit

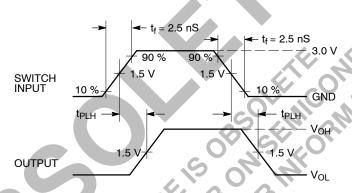


Figure 4. Propagation Delays

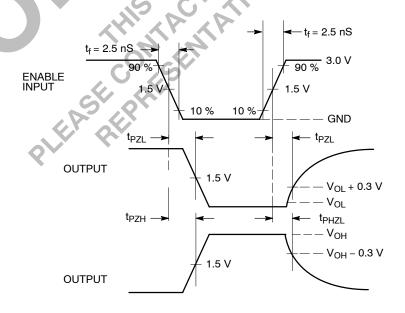
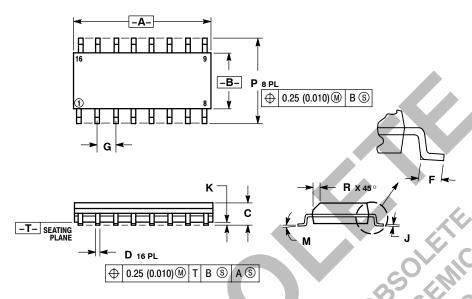


Figure 5. Enable/Disable Delays

PACKAGE DIMENSIONS

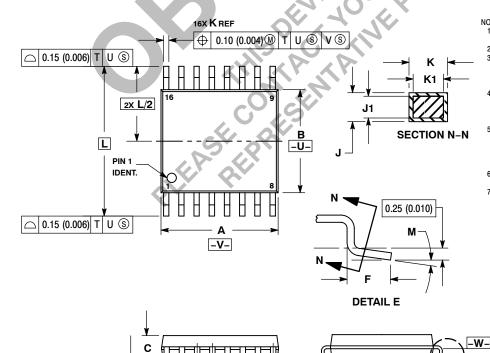
SOIC-16 **DW SUFFIX** CASE 751B-05 **ISSUE J**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES			
DIM	MIN	MAX	MIN	MAX			
Α	9.80	10.00	0.386	0.393			
В	3.80	4.00	0.150	0.157			
С	1.35	1.75	0.054	0.068			
D	0.35	0.49	0.014	0.019			
F	0.40	1.25	0.016	0.049			
G	1.27	BSC	0.050	BSC			
J	0.19	0.25	0.008	0.009			
K	0.10	0.25	0.004	0.009			
M	0°	7°	0°	7°			
Р	5.80	6.20	0.229	0.244			
R	0.25	0.50	0.010	0.019			
	W. T.						





G

NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- T 14.3M, 1902.

 CONTROLLING DIMENSION: MILLIMETER.

 DIMENSION A DOES NOT INCLUDE MOLD FLASH.

 PROTRUSIONS OR GATE BURRS. MOLD FLASH

 OR GATE BURRS SHALL NOT EXCEED 0.15
- ON GATE BURNS SHALL NOT EXCEED U.15
 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED
 0.25 (0.010) PER SIDE.
- 0.25 (0.010) FER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65 BSC		0.026	BSC	
Н	0.18	0.28	0.007	0.011	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
M	0°	8°	0°	8°	

http://onsemi.com

DETAIL E

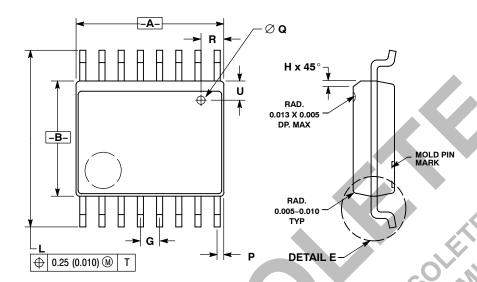
☐ 0.10 (0.004)

-T- SEATING PLANE

PACKAGE DIMENSIONS

QSOP-16 **QS SUFFIX**

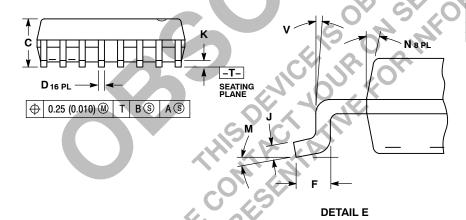
CASE 492-01 **ISSUE O**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 THE BOTTOM PACKAGE SHALL BE BIGGER THAN THE TOP PACKAGE BY 4 MILS (NOTE: LEAD SIDE ONLY). BOTTOM PACKAGE DIMENSION SHALL FOLLOW THE DIMENSION STATED IN THIS DRAWING.
- PLASTIC DIMENSIONS DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 6 MILS PER
- BOTTOM EJECTOR PIN WILL INCLUDE THE COUNTRY OF ORIGIN (COO) AND MOLD CAVITY I.D.

	INC	HES	MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.189	0.196	4.80	4.98
В	0.150	0.157	3.81	3.99
c	0.061	0.068	1.55	1.73
D	0.008	0.012	0.20	0.31
F	0.016	0.035	0.41	0.89
G	0.025	BSC	0.64	BSC
Ŧ	0.008	0.018	0.20	0.46
7	0.0098	0.0075	0.249	0.191
K	0.004	0.010	0.10	0.25
4	0.230	0.244	5.84	6.20
M	0°	8 °	0°	8°
N	0°	7°	0°	7°
P	0.007	0.011	0.18	0.28
Q	0.020	DIA	0.51 DIA	
R	0.025	0.035	0.64	0.89
U	0.025	0.035	0.64	0.89
٧	0°	8°	0°	8°



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